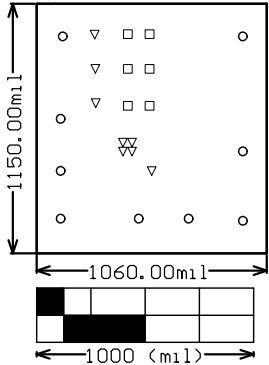


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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600113	REV: A	
LAYER NAME = M2006cubK9m1a1ons			
PLOT NAME = LP2998EVAL.GM11	GENERATED : 9/24/2013 11:11:41 AM		TEXAS INSTRUMENTS

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Layer Stack Up Detail for: LP2998EVAL.PcbDoc						
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
1060MIL X 1150MIL  
Number of Layers : 2  
MIN. TRACK WIDTH: 10 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 30 MIL  
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:  
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER  
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER  
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
COPPER THICKNESS (FINISHED):  
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)  
INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A  
DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER  
BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR:  
☒ GREEN ☐ BLUE ☐ OTHER  
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER  
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1  
☐ N.C. ROUTE ☒ V. SCORE  
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER  
ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

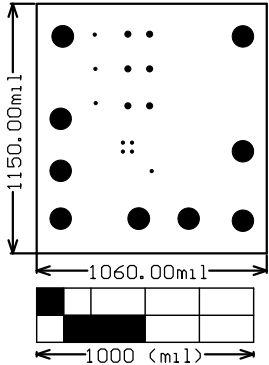
PROJECT TITLE: LP2998 Evaluation Board	
DESIGNED FOR: Public Release	
FILE NAME: LP2998EVAL.PcbDoc	
MODIFIED BY: Krypton Solutions	LAYOUT BY:
SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600113	REV: A	
LAYER NAME = M2006cubK9ptm1a			
PLOT NAME = LP2998EVAL.GM11	GENERATED : 9/24/2013 11:11:41 AM	TEXAS INSTRUMENTS	

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Layer Stack Up Detail for: LP2998EVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)

1060MIL X 1150MIL

Number of Layers : 2

MIN. TRACK WIDTH: 10 MIL

MIN. CLEARANCE: 8 MIL

MIN. VIA PAD SIZE: 30 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-4 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)

INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR:

☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs

TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



PROJECT TITLE:  
LP2998 Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LP2998EVAL.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION:  
10.0.0.27009

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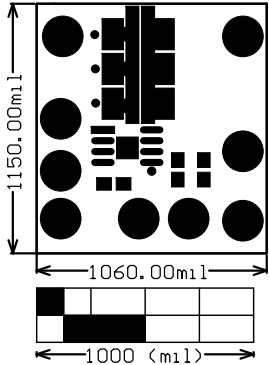


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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600113	REV: A	
LAYER NAME = M2006cubK9m1a1ons			
PLOT NAME = LP2998EVAL.GM11	GENERATED : 9/24/2013 11:11:41 AM		TEXAS INSTRUMENTS

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Layer Stack Up Detail for: LP2998EVAL.PcbDoc						
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
1060MIL X 1150MIL  
Number of Layers : 2  
MIN. TRACK WIDTH: 10 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 30 MIL  
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:  
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER  
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER  
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
COPPER THICKNESS (FINISHED):  
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)  
INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A  
DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER  
BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR:  
☒ GREEN ☐ BLUE ☐ OTHER  
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER  
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1  
☐ N.C. ROUTE ☒ V. SCORE  
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER  
ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

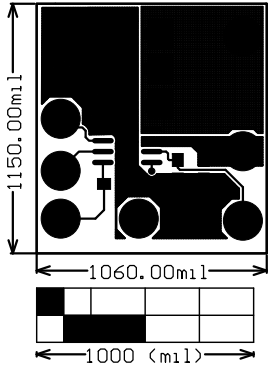
PROJECT TITLE: LP2998 Evaluation Board	
DESIGNED FOR: Public Release	
FILE NAME: LP2998EVAL.PcbDoc	
MODIFIED BY: Krypton Solutions	LAYOUT BY:
SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009

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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600113	REV: A	
LAYER NAME = M2006cubK9m1a1ons			
PLOT NAME = LP2998EVAL.GM11	GENERATED : 9/24/2013 11:11:41 AM		TEXAS INSTRUMENTS


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Layer Stack Up Detail for: LP2998EVAL.PcbDoc						
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
1060MIL X 1150MIL  
Number of Layers : 2  
MIN. TRACK WIDTH: 10 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 30 MIL  
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:  
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER  
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER  
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
COPPER THICKNESS (FINISHED):  
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)  
INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A  
DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER  
BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR:  
☒ GREEN ☐ BLUE ☐ OTHER  
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER  
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1  
☐ N.C. ROUTE ☒ V. SCORE  
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER  
ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



PROJECT TITLE:  
LP2998 Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LP2998EVAL.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION:  
10.0.0.27009

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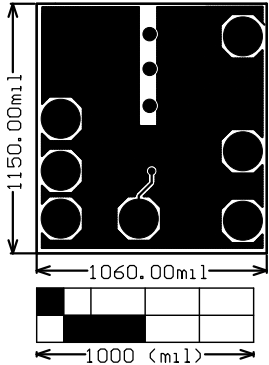
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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	SU600113	REV:	A	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.	
LAYER NAME = M2006cubK9m1a						
PLOT NAME = LP2998EVAL.GM11	GENERATED	: 9/24/2013	11:11:41 AM	TEXAS INSTRUMENTS		

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Layer Stack Up Detail for: LP2998EVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)

1060MIL X 1150MIL

Number of Layers : 2

MIN. TRACK WIDTH: 10 MIL

MIN. CLEARANCE: 8 MIL

MIN. VIA PAD SIZE: 30 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-4 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)

INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR:

☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL:

☐ CUT AND TRIM PER MECH LAYER 1

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



PROJECT TITLE:  
LP2998 Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LP2998EVAL.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION:  
10.0.0.27009

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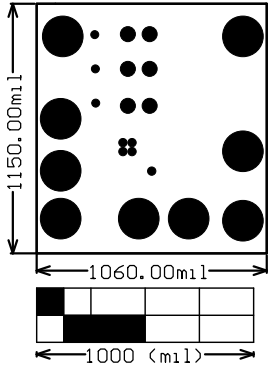
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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600113	REV: A	
LAYER NAME = M2006cubK9m1a1ons			
PLOT NAME = LP2998EVAL.GM11	GENERATED : 9/24/2013 11:11:41 AM		TEXAS INSTRUMENTS

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Layer Stack Up Detail for: LP2998EVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)

1060MIL X 1150MIL

Number of Layers : 2

MIN. TRACK WIDTH: 10 MIL

MIN. CLEARANCE: 8 MIL

MIN. VIA PAD SIZE: 30 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-4 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)

INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR:

☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL:

☐ CUT AND TRIM PER MECH LAYER 1

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



PROJECT TITLE:  
LP2998 Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LP2998EVAL.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION:  
10.0.0.27009

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